Design and Analysis of Low-Power Full Adder using Novel 10-T XOR-XNOR Cell

G.R.K. Prasad¹, N Krishna Teja², M Siva Kumar³,

¹Associate Professor, Koneru Lakshmaiah Education Foundation,
 ²MTech (VLSI)-(2019-21), K L UNIVERSITY,
 ³Associate professor, K l University,

Article History: Received: 11 January 2021; Revised: 12 February 2021; Accepted: 27 March 2021; Published online: 23 May 2021

Abstract: Many electronic devices are mostly used by the many humans and these become more important in our daily life. These electronics will have mostly comprised arithmetic circuits. For the multipliers, the adder is a traditional component for most of the circuits. Arithmetic circuits are significantly utilized by the data paths that uses one-third of power in the high-performance microprocessors. It is very important to enhance the performance of the adders which increase the overall performance significantly. To implement full adder (FA) circuits, hybrid logic is most widely used. The performance of hybrid FA is calculated in terms of delay, power, and driving capability is mostly dependent on the performance of XOR–XNOR circuit. In this paper, a high speed, low-power 10-T XOR–XNOR circuit is proposed, which provides full swing outputs simultaneously with improved delay performance. The performance of the proposed circuit is measured by simulating it Tanner EDA environment.

Keywords: personal digital assistants (PDAs), full adder (FA) circuits, XOR-XNOR circuit.

1. Introduction

The first approach becomes to be a settlement wafer manufacture business enterprise, but the enterprise economic backers wished the business enterprise to create IC (Integrated Circuit) plan apparatuses to assist fill the foundry. Because of its Caltech and UC Berkeley understudies, VLSI becomes a great pioneer withinside the digital plan mechanization (EDA) industry. It provided a cultured package deal of contraptions, to start with depending on the 'lambda-based' plan fashion-driven thru Carver Mead and Lynn Conway.

The apparatuses had been an integrated plan solution for IC plan and now no longer honestly factor gadgets or extra universally beneficial framework contraptions. An originator ought to adjust semiconductor stage polygons or doubtlessly motive schematics, at that factor run DRC and LVS, extricate parasitic from the layout and run Spice reenactment, at that factor back-touch upon the condition or door length adjustments into the motive schematic records base. Portrayal apparatuses had been integrated to create Frame Maker Data Sheets for Libraries. VLSI ultimately spun off the CAD and Library pastime into Compass Design Automation but it in no way arrived at IPO it become sold via way of means of Avanti Corp. VLSI's real plan contraptions had been simple now no longer completely to its ASIC commercial enterprise, but further in placing the bar for the commercial enterprise digital plan robotization (EDA) industry.



Figure: 1 A VLSI VL82C106 Super I/Ochip

At the factor, while VLSI and its number one ASIC rival, LSI Logic, had been constructing up the ASIC commercial enterprise, monetarily available contraptions could not bring the performance-critical to assist the real plan of many ASIC plans every 12 months without the business enterprise of a significant quantity of layout engineers. The organizations' development of automated layout gadgets become a normal "make in mild of the truth that there may be not anything to purchase" choice. The EDA commercial enterprise at lengthy remaining was given on top of things withinside the remaining part of the Eighties while Tangent Systems added its Tan Cell and Tan Gate items. In 1989, Tangent become procured via way of means of Cadence Design Systems (hooked up in 1988).

The VLSI's underlying health in plan contraptions, they had been now no longer pioneers in semiconductor fabricating innovation. VLSI had now no longer been opportune in constructing up a 1.0 μ m generating degree because the rest of the commercial enterprise moved to that math withinside the remaining part of the 80. VLSI

entered a drawn-out innovation business enterprise with Hitachi ultimately added a 1.0 μ m interplay and molecular library (in truth to a extra diploma a 1.2 μ m library with a 1.0 μ m door).

2. Hybrid Design:

In the hybrid model, the FA structure is isolated into three modules as demonstrated in Fig. 1. Module I creates going all out XOR and XNOR yields of two info flags (An and B) at the same time. These XOR–XNOR signals should have great driving capacities as these signs need to drive the other two modules. Module II and Module III are total and convey circuits that produce the total and convey yields (COUT), individually, utilizing the yields of Module I and third info signal (CIN). The fundamental bit of leeway of half breed style is that all the modules can be advanced at the individual level, and the number of semiconductors can be decreased, which lessens the inner force scattering nodes.



Figure 2: Block diagram of hybrid logic FA circuit

3. Proposed XOR–XNOR Circuit

The proposed XOR–XNOR circuit utilising ten semiconductors (10-T) seems in Fig. 2. The proposed XOR–XNOR circuit relies upon on CPL and cross-coupled layout. It makes use of pMOS (P1 and P2) and 3 nMOS (N3, N4, and N5) semiconductors on the XOR yield aspect and nMOS (N1 and N2) and 3 pMOS (P3, P4, and P5) on the XNOR yield aspect. At the XOR aspect, P1 and P2 are related in same as PTL, N4, and N5 as a restorer to provide a going all out yield and N3 as complaint semiconductor. Essentially, on the XNOR yield aspect, N1 and N2 semiconductors are related in same as PTL, P4, and P5 as a restorer to provide a going all out yield and N3 as complaint semiconductor. Essentially, on the XNOR yield aspect, N1 and N2 semiconductor. This circuit offers going all out XOR–XNOR yields on the identical time. For information the hobby of the proposed configuration, charging and liberating methods for XOR and XNOR yields seem in Table I. It consists of all of the methods which provide a midway swing and going all out on the yield hubs. For the data AB: "01," the semiconductors P2, N1, and P4 flip on. Semiconductors P2 and N1 byskip rationale "1" and rationale "0" at XOR and XNOR yields, individually, at the same time as semiconductor P4 activates the semiconductors P1, N2, and N4 flip on. Semiconductors P1 and N2 byskip rationale "1" and rationale "1" and rationale "0" at XOR and XNOR yields, individually, at the same time as semiconductor P3 to byskip the feeble rationale "0" (- Vthp) on the XNOR yield. Likewise, for the data AB: "10," semiconductors P1, N2, and N4 flip on. Semiconductor N4 activates the semiconductor N3 which passes the frail rationale "1" (VDD–Vthn) on the XOR yield.



Figure 3: Proposed XOR-XNOR circuit

Inputs	Path		Path	
AB	XOR	XOR	XOR	XNOR
	(Full	(Partial	(Full	(Partial
	Swing)	Swing)	Swing)	Swing)
00	N3	P1, P2	P4, P5	-
01	P2	-	N1	P4, P3
10	P1	N4, N3	N2	-
11	N4, N5	-	P3	N1,N2

Table 1: charging and discharging paths for XOR and XNOR outputs

For those inputs (AB: "01" and "10"), the vulnerable common sense outputs will now no longer have an effect on the output swing as paths are to be had for complete swing outputs. For the enter AB: "00," the transistors P1, P2, P4, and P5 flip on. P1 and P2 byskip vulnerable common sense "0" (-Vthp) on the XOR output, at the same time as P5 and P4 byskip complete common sense "1" at XNOR output and the inner node X. Logic "1" at node X activates the transistor N3 and a robust common sense "0" is exceeded on the XOR output to make it complete swing. Similarly, for enter AB: "11," transistors N1, N2, N4, and N5 flip on. The transistors N1 and N2 byskip vulnerable common sense "1" (VDD-Vthn) for the XNOR output, at the same time as the XOR node discharges absolutely thru N4 and N5. Logic "0" additionally passes to the inner node X, which reasons transistor P3 to be grew to become on and passes the entire common sense "1" on the XNOR output.

4. Results:



Figure 4: Schematic of XOR-XNOR



Figure 5: Waveform:



Figure 6: Schematic of Full Adder



Figure 7: Waveform:

5. Power Results

Power Results vdd gnd from time 1e-007 to 0 Average power consumed -> 5.777151e-005 watts Max power 1.163025e-004 at time 0 Min power 7.595088e-007 at time 1e-007

Figure 8: Power report at vdd 1.8v

* BEGIN NON-GRAPHICAL DATA

```
Power Results
vdd gnd from time 1e-007 to 0
Average power consumed -> 5.280274e-003 watts
Max power 1.056668e-002 at time 0
Min power 6.127995e-006 at time 1e-007
```

Figure 9: Power report at vdd 5v

6. Conclusion

A new 10-T XOR–XNOR circuit turned into proposed which furnished complete swing outputs simultaneously. Using the proposed XOR–XNOR circuit, FA mobileular primarily based totally on hybrid common sense layout fashion have been additionally proposed. The overall performance of the proposed XOR–XNOR circuit and the FA cells turned into examined via way of means of simulating them in tanner EDA tool.

References:

[1] A. P. Chandrakasan, S. Sheng, and R. W. Brodersen, "Low-power CMOS digital design," IEICE Trans. Electron., vol. 75, no. 4, pp. 371–382, 1992.

[2] R. Zimmermann and W. Fichtner, "Low-power logic styles: CMOS versus pass-transistor logic," IEEE J. Solid-State Circuits, vol. 32, no. 7, pp. 1079–1090, Jul. 1997.

[3] S. Goel, A. Kumar, and M. A. Bayoumi, "Design of robust, energyefficient full adders for deepsubmicrometer design using hybrid-CMOS logic style," IEEE Trans. Very Large Scale Integr. (VLSI) Syst., vol. 14, no. 12, pp. 1309–1321, Dec. 2006.

[4] C.-H. Chang, J. Gu, and M. Zhang, "A review of 0.18-μm full adder performances for tree structured arithmetic circuits," IEEE Trans. Very Large Scale Integr. (VLSI) Syst., vol. 13, no. 6, pp. 686–695, Jun. 2005.

[5] N. Zhuang and H. Wu, "A new design of the CMOS full adder," IEEE J. Solid-State Circuits, vol. 27, no. 5, pp. 840–844, May 1992.

[6] M. Aguirre-Hernandez and M. Linares-Aranda, "CMOS full-adders for energy-efficient arithmetic applications," IEEE Trans. Very Large Scale Integr. (VLSI) Syst., vol. 19, no. 4, pp. 718–721, Apr. 2011.

[7] V. Foroutan, M. Taheri, K. Navi, and A. A. Mazreah, "Design of two low-power full adder cells using GDI structure and hybrid CMOS logic style," Integration, vol. 47, no. 1, pp. 48–61, Jan. 2014.

[8] M. Agarwal, N. Agrawal, and M. A. Alam, "A new design of low power high speed hybrid CMOS full adder," in Proc. Int. Conf. Signal Process. Integr. Netw. (SPIN), Feb. 2014, pp. 448–452. [9] M. Vesterbacka, "A 14-transistor CMOS full adder with full voltageswing nodes," in Proc. IEEE Workshop Signal Process. Systems. Design Implement. (SiPS), Oct. 1999, pp. 713–722.

[10] M. Zhang, J. Gu, and C.-H. Chang, "A novel hybrid pass logic with static CMOS output drive full-adder cell," in Proc. Int. Symp. Circuits Syst. (ISCAS), vol. 5, May 2003, p. 5.

[11] C.-K. Tung, S.-H. Shieh, and C.-H. Cheng, "Low-power high-speed full adder for portable electronic applications," Electron. Lett., vol. 49, no. 17, pp. 1063–1064, Aug. 2013.

[12] P. Bhattacharyya, B. Kundu, S. Ghosh, V. Kumar, and A. Dandapat, "Performance analysis of a low-power high-speed hybrid 1-bit full adder circuit," IEEE Trans. Very Large Scale Integr. (VLSI) Syst., vol. 23, no. 10, pp. 2001–2008, Oct. 2015.

[13] D. Radhakrishnan, "Low-voltage low-power CMOS full adder," IEE Proc.-Circuits, Devices Syst., vol. 148, no. 1, pp. 19–24, Feb. 2001.

[14] M. A. Valashani and S. Mirzakuchaki, "A novel fast, low-power and high-performance XOR-XNOR cell," in Proc. IEEE Int. Symp. Circuits Syst. (ISCAS), May 2016, pp. 694–697.

[15] H. Naseri and S. Timarchi, "Low-power and fast full adder by exploring new XOR and XNOR gates," IEEE Trans. Very Large Scale Integr. (VLSI) Syst., vol. 26, no. 8, pp. 1481–1493, Aug. 2018.

[16] H. Tien Bui, Y. Wang, and Y. Jiang, "Design and analysis of low-power 10-transistor full adders using novel XOR-XNOR gates," IEEE Trans. Circuits Syst. II, Analog Digit. Signal Process., vol. 49, no. 1, pp. 25–30, 2002.